

SNLS392D - JUNE 1998-REVISED APRIL 2013

# DS16F95, DS36F95 EIA-485/EIA-422A Differential Bus Transceiver

Check for Samples: DS16F95, DS36F95

## **FEATURES**

- Meets EIA-485 and EIA-422A
- Meets SCSI-1 (5 MHZ) Specifications
- **Designed for Multipoint Transmission**
- Wide Positive and Negative Input/Output Bus Voltage Ranges
- **Thermal Shutdown Protection**
- **Driver Positive and Negative Current-Limiting**
- **High Impedance Receiver Input**
- **Receiver Input Hysteresis of 50 mV Typical**
- **Operates from Single 5.0V Supply**
- **Reduced Power Consumption**
- Pin Compatible with DS3695 and SN75176A
- **Military Temperature Range Available**
- **Qualified for MIL-STD 883C**
- Standard Military Drawings (SMD) Available
- Available in 8-Pin CDIP (NAB0008A) or SOIC (D) Package

## DESCRIPTION

The DS16F95/DS36F95 Differential Bus Transceiver is a monolithic integrated circuit designed for bidirectional data communication on balanced multipoint bus transmission lines. The transceiver meets both EIA-485 and EIA-422A standards.

The DS16F95/DS36F95 offers improved performance due to the use of L-FAST bipolar technology. The L-FAST technology allows for higher speeds and lower currents by minimizing gate delay times. Thus, the DS16F95 and DS36F95 consume less power, and feature an extended temperature range as well as improved specifications.

The DS16F95/DS36F95 combines a Tri-state differential line driver and a differential input line receiver, both of which operate from a single 5.0V power supply. The driver and receiver have an active Enable that can be externally connected to function as a direction control. The driver differential outputs and the receiver differential inputs are internally connected to form differential input/output (I/O) bus ports that are designed to offer minimum loading to the bus whenever the driver is disabled or when  $V_{CC}$ = 0V. These ports feature wide positive and negative common mode voltage ranges, making the device suitable multipoint applications for in noisv environments.

The driver is designed to accommodate loads of up to 60 mA of sink or source current and features positive and negative current limiting in addition to thermal shutdown for protection from line fault conditions.

The DS16F95/DS36F95 can be used in transmission line applications employing the DS96F172 and the DS96F174 quad differential line drivers and the DS96F173 and DS96F175 quad differential line receivers.



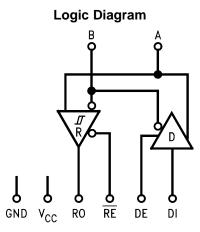
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### **Function Tables**

### Table 1. Driver<sup>(1)</sup>

Driver Input	Enable	Out	puts
DI	DE	Α	В
Н	н	Н	L
L	Н	L	Н
Х	L	Z	Z

(1) H = High Level L = Low Level

X = Immaterial

Z = High Impedance (Off)

### Table 2. Receiver<sup>(1)</sup>

Differential Inputs	Enable	Output
A–B	RE	RO
V <sub>ID</sub> ≥ 0.2V	L	Н
$V_{ID} \leq -0.2V$	L	L
X	Н	Z

(1) H = High Level L = Low Level

X = Immaterial Z = High Impedance (Off)

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam

Absolute Maximum Ratings<sup>(1)(2)</sup>

Storage Temperature Range		−65°C to +175°C
Lead Temperature (Soldering, 60 sec.)		300°C
Maximum Package Power Dissipation <sup>(3)</sup> at 25°C	CDIP Package	1300 mW
	SOIC Package	735 mW
Supply Voltage	· · ·	7.0V
Input Voltage (Bus Terminal)		+15V/-10V
Enable Input Voltage		5.5V

(1) Absolute Maximum Ratings are those values beyond which the safety of the device cannot be ensured. They are not meant to imply that the devices should be operated at these limits. The tables of Electrical Characteristics provide conditions for actual device operation.

(2) Specifications for the 883 version of this product are listed separately on the following pages.

during storage or handling to prevent electrostatic damage to the MOS gates.

(3) Derate CDIP package 8.7 mW/°C above 25°C.Derate SOIC package 5.88 mW/°C above 25°C.

### **Recommended Operating Conditions**

		Min	Тур	Max	Units
Supply Voltage (V <sub>CC</sub> )	DS36F95	4.75	5.0	5.25	V
	DS16F95	4.50	5.0	5.50	V
Voltage at Any Bus Terminal (Separately	or Common Mode) (V <sub>I</sub> or V <sub>CM</sub> )	-7.0		+12	V
Differential Input Voltage (VID)				±12	V
Output Current HIGH (I <sub>OH</sub> )	Driver			-60	mA
	Receiver			-400	μA
Output Current LOW (I <sub>OL</sub> )	Driver			60	mA
	Receiver			16	mA
Operating Temperature (T <sub>A</sub> )	DS36F95	0	+25	+70	°C
	DS16F95	-55	+25	+125	°C



## Driver Electrical Characteristics<sup>(1)(2)</sup>

Over recommended supply voltage and operating temperature ranges, unless otherwise specified

Symbol	Parameter	Conditions		Min	Тур	Max	Units
VIH	Input Voltage HIGH			2.0			V
VIL	Input Voltage LOW					0.8	V
V <sub>OH</sub>	Output Voltage HIGH	I <sub>OH</sub> = −55 mA	0°C to +70°C	3.0			V
V <sub>OL</sub>	Output Voltage LOW	I <sub>OL</sub> = 55 mA	0°C to +70°C			2.0	V
V <sub>IC</sub>	Input Clamp Voltage	I <sub>I</sub> = −18 mA				-1.3	V
V <sub>OD1</sub>	Differential Output Voltage	$I_0 = 0 \text{ mA}$				6.0	V
V <sub>OD2</sub>	Differential Output Voltage	$R_L = 100\Omega$ , See Figure 1		2.0	2.25		V
		$R_L = 54\Omega$ ,See Figure 1		1.5	2.0		v
$\Delta  V_{OD} $	Change in Magnitude of Differential					±0.2	V
	Output Voltage <sup>(3)</sup>	Figure 1	-55°C to +125°C			±0.4	
V <sub>OC</sub>	Common Mode Output Voltage <sup>(4)</sup>					3.0	V
$\Delta  V_{OC} $	Change in Magnitude of Common Mode Output Voltage <sup>(3)</sup>					±0.2	V
I <sub>O</sub> C	Output Current <sup>(5)</sup> (Includes	Output Disabled	$V_0 = +12V$			1.0	— mA
	Receiver I <sub>I</sub> )		V <sub>O</sub> = -7.0V			-0.8	
I <sub>IH</sub>	Input Current HIGH	V <sub>1</sub> = 2.4V				20	μA
IIL	Input Current LOW	$V_{I} = 0.4V$				-50	μA
l <sub>os</sub>	Short Circuit Output Current <sup>(6)</sup>	V <sub>O</sub> = -7.0V				-250	
		$V_{\rm O} = 0V$				-150	mA
		$V_{O} = V_{CC}$				150	
		V <sub>O</sub> = +12V				250	
I <sub>CC</sub>	Supply Current (Total Package)	No Load, All Inputs Open	DE = 2V, $\overline{RE}$ = 0.8V Outputs Enabled			28	~^
I <sub>CCX</sub>			$DE = 0.8V, \overline{RE} = 2V$ Outputs Disabled			25	mA

(1) Unless otherwise specified min/max limits apply across the -55°C to +125°C temperature range for the DS16F95 and across the 0°C to +70°C range for the DS36F95. All typicals are given for  $V_{CC}$  = 5V and  $T_A$  = 25°C.

All currents into the device pins are positive; all currents out of the device pins are negative. All voltages are referenced to ground (2) unless otherwise specified.

(3)  $\Delta |V_{OD}|$  and  $\Delta |V_{OC}|$  are the changes in magnitude of  $V_{OD}$  and  $V_{OC}$ , respectively, that occur when the input is changed from a high level to a low level.

In TIA/EIA-422A and TIA/EIA-485 Standards, V<sub>OC</sub>, which is the average of the two output voltages with respect to ground, is called (4) output offset voltage, V<sub>OS</sub>. Refer to TIA/EIA-485 Standard for exact conditions.

(5)

Only one output at a time should be shorted. (6)



## **Driver Switching Characteristics**

 $V_{CC} = 5.0V, T_A = 25^{\circ}C$ 

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Symbol	Parameter	Conditions	Min	Тур	Max	Units
t <sub>DD</sub>	Differential Output Delay Time	$R_L = 60\Omega$ , See Figure 2	8.0	15	20	ns
t <sub>TD</sub>	Differential Output Transition Time		8.0	15	22	ns
t <sub>PLH</sub>	Propagation Delay Time, Low-to-High Level Output	$R_L = 27\Omega$ , See Figure 4	6.0	12	16	ns
t <sub>PHL</sub>	Propagation Delay Time, High-to-Low Level Output	_	6.0	12	16	ns
t <sub>ZH</sub>	Output Enable Time to High Level	$R_L = 110\Omega$ , See Figure 5		25	32	ns
t <sub>ZL</sub>	Output Enable Time to Low Level	$R_L = 110\Omega$ , See Figure 6		25	32	ns
t <sub>HZ</sub>	Output Disable Time from High Level	$R_L = 110\Omega$ , See Figure 5		20	25	ns
t <sub>LZ</sub>	Output Disable Time from Low Level	$R_L = 110\Omega$ , See Figure 6		20	25	ns
t <sub>LZL</sub>	Output Disable Time from Low Level with Load Resistor to GND	Load per Figure 5 Timing per Figure 6		300		ns
t <sub>SKEW</sub>	Skew (Pulse Width Distortion)	$R_L = 60\Omega$ , See Figure 2		1.0	4.0	ns

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### **Receiver Electrical Characteristics**

Over recommended supply voltage and operating temperature ranges, unless otherwise specified

Symbol	Parameter	Co	nditions	Min	Тур	Max	Units
V <sub>TH</sub>	Differential Input High Threshold Voltage	$V_0 = 2.7V, I_0 = -0.4 m$	$V_0 = 2.7V, I_0 = -0.4 \text{ mA}$			0.2	V
V <sub>TL</sub>	Differential Input Low Threshold Voltage See <sup>(1)</sup>	$V_{O} = 0.5V, I_{O} = 8.0 \text{ mA}$		-0.2			V
V <sub>T+</sub> -V <sub>T-</sub>	Hysteresis See <sup>(2)</sup>	$V_{CM} = 0V$		35	50		mV
V <sub>IH</sub>	Enable Input Voltage HIGH			2.0			V
V <sub>IL</sub>	Enable Input Voltage LOW					0.8	V
V <sub>IC</sub>	Enable Input Clamp Voltage	I <sub>I</sub> = −18 mA				-1.3	V
V <sub>OH</sub>	Output Voltage HIGH	V <sub>ID</sub> = 200 mV,	0°C to +70°C	2.8			V
		I <sub>OH</sub> = −400 µA, See Figure 2	−55°C to +125°C	2.5			
V <sub>OL</sub>	Output Voltage LOW	V <sub>ID</sub> = −200 mV, See Figure 2	I <sub>OL</sub> = 8.0 mA			0.45	V
			I <sub>OL</sub> = 16 mA			0.50	v
I <sub>OZ</sub>	High Impedance State Output	$V_0 = 0.4V$ to 2.4V	$V_0 = 0.4V$ to 2.4V			±20	μA
l <sub>l</sub>	Line Input Current See (3)	Other Input = 0V	V <sub>I</sub> = +12V			1.0	
			V <sub>I</sub> = -7.0V			0.8	mA
I <sub>IH</sub>	Enable Input Current HIGH	V <sub>IH</sub> = 2.7V				20	μA
IIL	Enable Input Current LOW	$V_{IL} = 0.4V$				-50	μA
R <sub>I</sub>	Input Resistance			14	18	22	kΩ
l <sub>os</sub>	Short Circuit Output Current	See <sup>(3)</sup>		-15		-85	mA
I <sub>CC</sub>	Supply Current (Total Package)	No Load, All Inputs Open	$DE = 2V, \overline{RE} = 0.8V$ Outputs Enabled			28	<b>m</b> ^
I <sub>CCX</sub>			$DE = 0.8V, \overline{RE} = 2V$ Outputs Disabled			25	mA

(1) The algebraic convention, where the less positive (more negative) limit is designated minimum, is used in this data sheet for common mode input voltage and threshold voltage levels only.

(2) Hysteresis is the difference between the positive-going input threshold voltage, V<sub>T</sub>+, and the negative-going input threshold voltage, V<sub>T</sub>-.

(3) Refer to TIA/EIA-485 Standard for exact conditions.



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## **Receiver Switching Characteristics**

 $V_{CC}$  = 5.0V,  $T_A$  = 25°C

Symbol	Parameter	Conditions	Min	Тур	Max	Units
t <sub>PLH</sub>	Propagation Delay Time, Low-to-High Level	$V_{ID} = 0V$ to +3.0VC <sub>L</sub> = 15 pF,	14	19	24	ns
	Output	See Figure 7	14	19	24	ns
t <sub>PHL</sub>	Propagation Delay Time, High-to-Low Level Output					
t <sub>ZH</sub>	Output Enable Time to High Level	C <sub>L</sub> = 15 pF, See Figure 8		10	16	ns
t <sub>ZL</sub>	Output Enable Time to Low Level			12	18	ns
t <sub>HZ</sub>	Output Disable Time from High Level	$C_L = 5.0 \text{ pF}$ , See Figure 8		12	20	ns
t <sub>LZ</sub>	Output Disable Time from Low Level			12	18	ns
t <sub>PLH</sub> -t <sub>PHL</sub>	Pulse Width Distortion (SKEW)	See Figure 7		1.0	4.0	ns

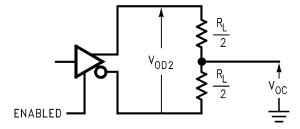
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### **Parameter Measurement Information**





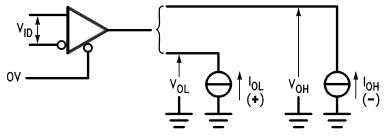


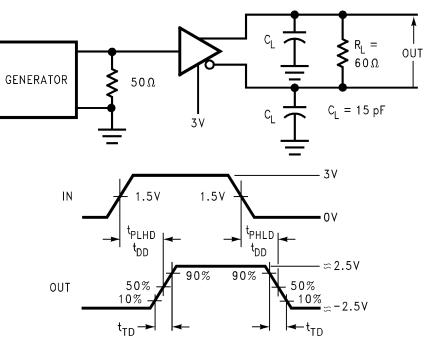
Figure 2. Receiver  $V_{\text{OH}}$  and  $V_{\text{OL}}$ 

(1) All diodes are 1N916 or equivalent.

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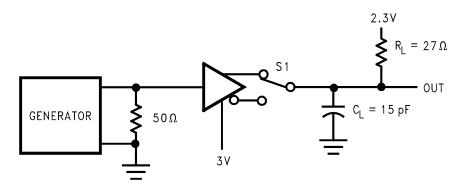


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 $t_{SKEW} = |t_{PLHD} - t_{PHLD}|$ 

Figure 3. Driver Differential Output Delay and Transition Times<sup>(2)(3)</sup>



(3) DS16F95/DS36F95 Driver enable is Active-High

<sup>(2)</sup> The input pulse is supplied by a generator having the following characteristics: PRR = 1.0 MHz, 50% duty cycle, tr  $\leq$  6.0 ns, tf  $\leq$  6.0 ns, ZO = 50 $\Omega$ .

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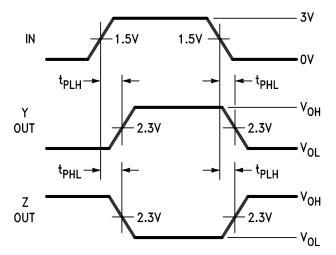
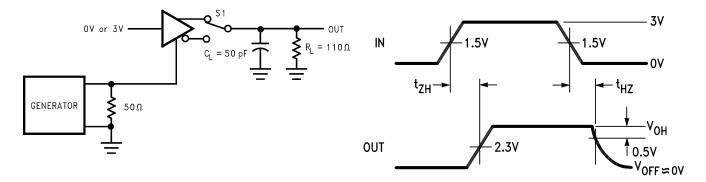
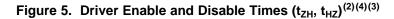


Figure 4. Driver Propagation Times<sup>(2)(4)</sup>





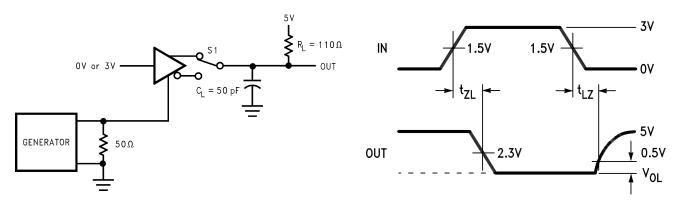
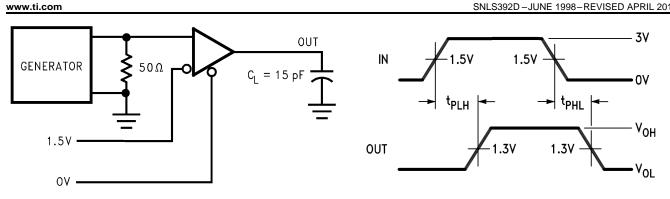


Figure 6. Driver Enable and Disable Times  $(t_{ZL}, t_{LZ}, t_{LZL})^{(5)(6)(7)}$ 

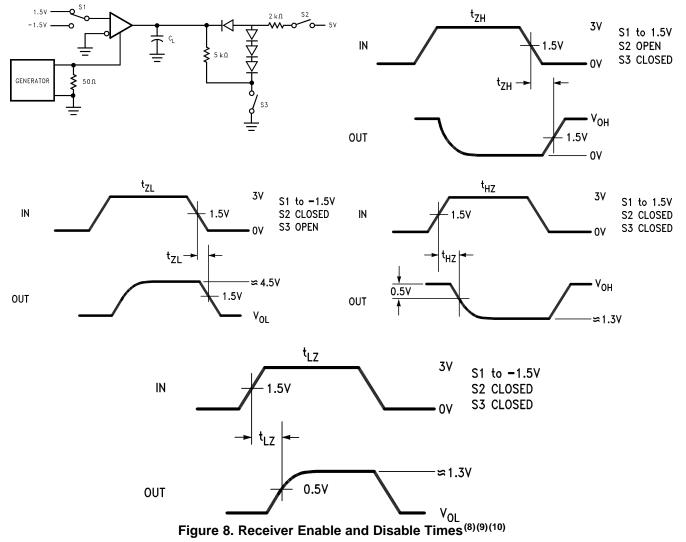
(4) CL includes probe and stray capacitance

- (5) The input pulse is supplied by a generator having the following characteristics: PRR = 1.0 MHz, 50% duty cycle, tr  $\leq$  6.0 ns, tf  $\leq$  6.0 ns, ZO = 50 $\Omega$ .
- (6) CL includes probe and stray capacitance
- (7) DS16F95/DS36F95 Driver enable is Active-High
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- The input pulse is supplied by a generator having the following characteristics: PRR = 1.0 MHz, 50% duty cycle, tr ≤ 6.0 ns, tf ≤ 6.0 ns, (8)  $ZO = 50\Omega$ .
- CL includes probe and stray capacitance (9)
- (10) All diodes are 1N916 or equivalent.

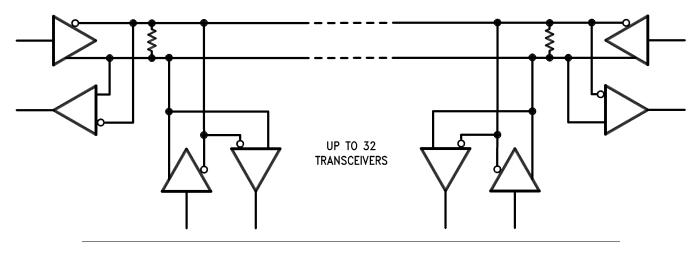
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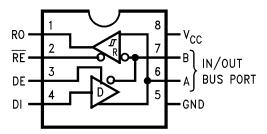
### **Typical Application**



## NOTE

The line should be terminated at both ends in its characteristic impedance, typically  $120\Omega$ . Stub lengths off the main line should be kept as short as possible.

### **Connection Diagram**



8-Lead Dual-In-Line Package or Small Outline Molded Package See Package Number J08A, or M08



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Cł	hanges from Revision C (April 2013) to Revision D	Page
•	Changed layout of National Data Sheet to TI format	12

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